

2SC5584

Silicon NPN triple diffusion mesa type

For horizontal deflection output

■ Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide safe operation area

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

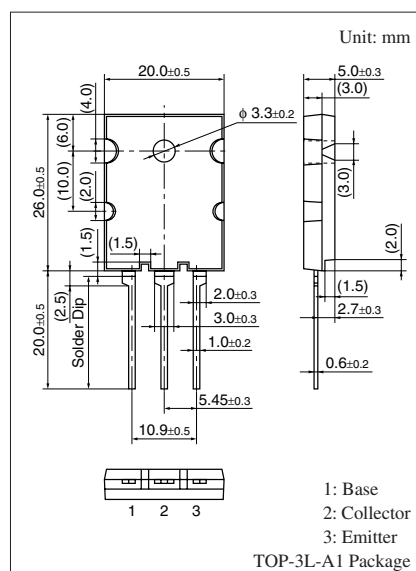
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	1 500	V
Collector-emitter voltage (E-B short)	V _{CES}	1 500	V
Collector-emitter voltage (Base open)	V _{CEO}	600	V
Emitter-base voltage (Collector open)	V _{EBO}	7	V
Base current	I _B	8	A
Collector current	I _C	20	A
Peak collector current *	I _{CP}	30	A
Collector power dissipation	P _C	150	W
		3.5	
T _a = 25°C			
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	−55 to +150	°C

Note) *: Non-repetitive peak collector current

■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1\,000\text{ V}, I_E = 0$			50	μA
		$V_{CB} = 1\,500\text{ V}, I_E = 0$			1	mA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 7\text{ V}, I_C = 0$			50	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = 5\text{ V}, I_C = 10\text{ A}$	7		14	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10\text{ A}, I_B = 2.5\text{ A}$			3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 10\text{ A}, I_B = 2.5\text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10\text{ V}, I_C = 0.1\text{ A}, f = 0.5\text{ MHz}$		3		MHz
Storage time	t_{stg}	$I_C = 10\text{ A}$, Resistance loaded			2.7	μs
Fall time	t_f	$I_{B1} = 2.5\text{ A}, I_{B2} = -5.0\text{ A}$			0.2	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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